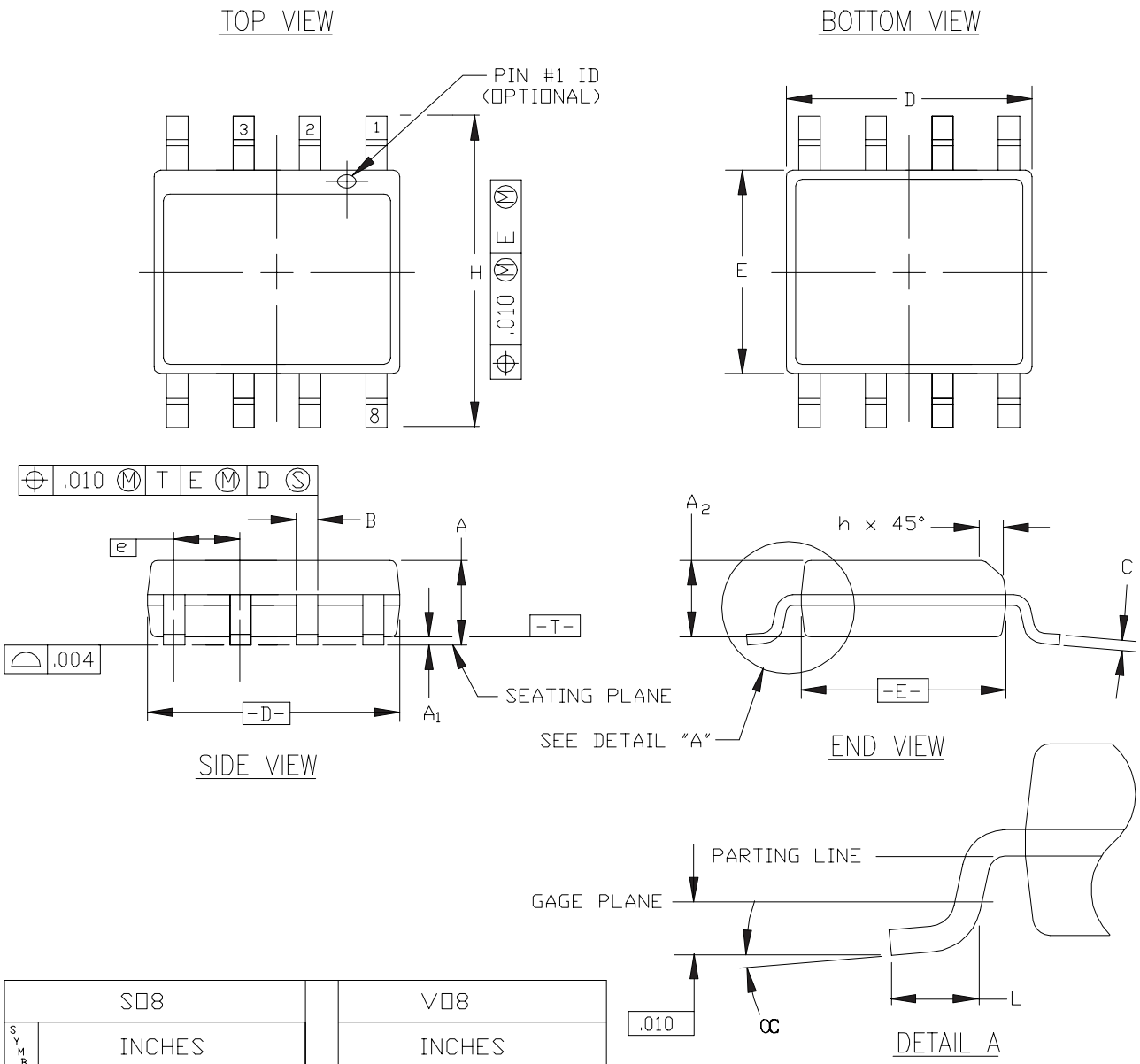
SOIC (SO8) and TSOP (VO8) Packages



SYMBOL	SO8 INCHES MIN.	SO8 INCHES NOM.	SO8 INCHES MAX.	VO8 INCHES MIN.	VO8 INCHES NOM.	VO8 INCHES MAX.
A	.059	.064	.068	—	—	.047
A_1	.004	.006	.0098	.002	.004	.006
A_2	.055	.058	.061	.037	.039	.044
B	.013	.016	.020	.0138	—	.0192
C	.0075	.008	.0098	.0075	—	.0089
D	.189	.194	.196	.189	.194	.196
E	.150	.155	.157	.150	.155	.157
e	.050 BSC			.050 BSC		
H	.229	.236	.244	.230	.236	.244
h	.010	.013	.019	.010	.013	.019
L	.016	.025	.035	.016	.025	.035
α	0°	5°	8°	0°	—	8°
REF.	JEDEC MS-012			—		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M–1982.
2. DIMENSION 'D' DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .006" PER SIDE.
3. DIMENSION 'E' DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .010 INCH PER SIDE.
4. LEAD FINISH: SOLDER PLATE

8 LEAD SOIC/TSOP (SO8, VO8)

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